AMENDMENTS TO THE CLAIMS

Claim 1 (Currently Amended) A method for manufacturing a printed wiring board which includes forming a thermosetting resin layer so as to fill spaces between circuit patterns formed on a surface of the printed wiring board, heating and curing the resin layer, and then polishing the cured resin layer covering the circuit patterns, thereby exposing the circuit patterns, wherein the step of heating and curing the resin layer comprises:

maintaining the resin layer at a non-curable temperature range between 100°C-140°C where the resin layer is pressed via a smoothing plate in a reduced pressure environment;

heating the resin layer in the pressed state to a curing temperature at which the resin layer is cured;

introducing outside air into the reduced pressure environment while maintaining the pressed state and the curing temperature;

reducing the pressure applied to the smoothing plate while maintaining the curing temperature; and

cooling the resin layer,

wherein a metallic foil with a roughened surface facing the resin layer is superposed on the resin layer.

Claim 2 (Previously Presented) The method for manufacturing a printed wiring board according to claim 1, wherein an applied pressure to the smoothing plate is increased in predetermined stages of pressure change.

Claim 3 (Previously Presented) The method for manufacturing a printed wiring board according to claim 2, wherein the resin layer is formed by adhering a liquid resin to the printed wiring board so as to fill spaces between the circuit patterns.

Claim 4 (Previously Presented) The method for manufacturing a printed wiring board according to claim 1, wherein the resin layer is formed by superposing a semi-cured resin sheet on the printed wiring board.

Claim 5 (Previously Presented) The method for manufacturing a printed wiring board according to claim 3, wherein the metallic foil is formed with a different type of metal than the circuit patterns.

Claim 6 (Previously Presented) The method for manufacturing a printed wiring board according to claim 4, wherein the metallic foil is formed with a different type of metal than the circuit patterns.

Claim 7 (Previously Presented) The method for manufacturing a printed wiring board according to claim 1 wherein the reduced pressure environment is provided by a reduced pressure chamber.

Claim 8 (Previously Presented) The method for manufacturing a printed wiring board according to claim 1, wherein the resin layer is formed by adhering a liquid resin to the printed wiring board so as to fill spaces between the circuit patterns.

Claim 9 (Previously Presented) The method for manufacturing a printed wiring board according to claim 8, wherein the metallic foil is formed with a different type of metal than the circuit patterns.

Claim 10 (Previously Presented) The method for manufacturing a printed wiring board according to claim 2, wherein the resin layer is formed by superposing a semi-cured resin sheet on the printed wiring board.

Claim 11 (Previously Presented) The method for manufacturing a printed wiring board according to claim 10, wherein the metallic foil is formed with a different type of metal than the circuit patterns.

Claims 12-19 (Canceled)